

## “MicrobondGecko” – Leadfree Die-Attach Adhesive for Power Devices

Today Umicore is known globally as one of the most innovative manufacturers of high-quality materials for semiconductor chip bonding. The exceptional know-how in the manufacturing and processing of these critical materials has given Umicore a unique opportunity to become the undisputed leader in the development and application of specialized Die-Attach materials. The excellent quality of the products ensures process-reliable and, consequently, more economical mounting of high-performance components. Continuous innovations underpin high standards and provide a continuously improving quality.

The combination of metals expertise coupled with strong chemical capabilities have made Umicore a world leader in the production of these Die-Attach materials. With that basis Umicore was in the position to develop a new product that could be considered as a break through in the microelectronic industry.

The worlds first **Die-Attach Adhesive for power devices** – totally lead free – a substitute for high temperature lead containing soft solders.

This adhesives series can be processed like conventional high-lead containing solders. In comparison to joints made out of solder pastes, adhesives exhibit strong advantages like a very low void rate, a high adhesion strength and an outstanding interface quality. A high thermal fatigue resistance and therefore a high reliability of the package will be achieved.

**MicrobondGecko** – A perfect drop-in solution. Easy to apply, by using the existing dispensing equipment.

